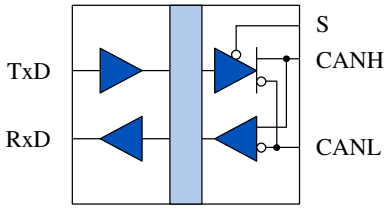
High-Speed, Low-Power Isolated CAN Transceiver

Functional Diagram



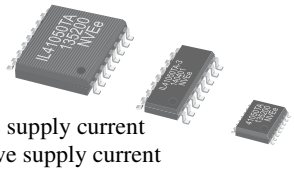
IL41050TA

V_{DD2} (V)	TxD[1]	S	CANH	CANL	Bus State	RxD
4.75 to 5.25	↓	Low[2]	High	Low	Dominant	Low
4.75 to 5.25	X	High	$V_{DD2}/2$	$V_{DD2}/2$	Recessive	High
4.75 to 5.25	↑	X	$V_{DD2}/2$	$V_{DD2}/2$	Recessive	High
<2V (no pwr)	X	X	0<V<2.5	0<V<2.5	Recessive	High
2<V_{DD2}<4.75	>2V	X	0<V<2.5	0<V<2.5	Recessive	High

Table 1. Function table.

Notes:
1. TxD input is edge triggered: ↑ = Logic Lo to Hi, ↓ = Hi to Lo
2. Valid for logic state as described or open circuit

X = don't care



Features

- 180 ns typical loop delay
- 70 mA maximum bus-side dynamic supply current
- 12 mA maximum quiescent recessive supply current
- 1 Mbps
- Fully compliant with the ISO 11898 CAN standard
- –55 °C to +125 °C operating temperature
- 3 V to 5.5 V power supplies
- >110-node fan-out
- 44000 year barrier life
- ±500 V CDM ESD
- 50 kV/µs typ.; 30 kV/µs min. common mode transient immunity
- No carrier or clock for low emissions and EMI susceptibility
- Silent mode to disable transmitter
- Transmit data (TxD) dominant time-out function
- Edge triggered, non-volatile input improves noise performance
- Thermal shutdown protection
- Bus power short-circuit protection
- 2500 V_{RMS} isolation voltage
- IEC 60747-17 (VDE 0884-17):2021-10 certified; UL 1577 recognized
- QSOP, 0.15" SOIC, or 0.3" True 8™ mm 16-pin packages

Applications

- Factory automation
- Battery management systems
- Noise-critical CAN
- DeviceNet

Description

The IL41050TA is a galvanically isolated, CAN (Controller Area Network) transceiver, designed as the interface between the CAN protocol controller and the physical bus.

The wide-body version provides true 8 mm creepage. Narrow-body and QSOP packages offer unprecedented miniaturization.

The IL41050 family provides isolated differential transmit capability to the bus and isolated differential receive capability to the CAN controller via NVE's patented* spintronic Giant Magnetoresistance (GMR) technology.

A unique ceramic/polymer composite barrier provides excellent isolation and virtually unlimited barrier life.

Advanced features facilitate reliable bus operation. Unpowered nodes do not disturb the bus, and a unique non-volatile programmable power-up feature prevents unstable nodes. The devices also have a hardware-selectable silent mode that disables the transmitter.

Designed for harsh CAN and DeviceNet environments, IL41050TA transceivers have transmit data dominant time-out, bus pin transient protection, a rugged Charged Device Model ESD rating, thermal shutdown protection, and short-circuit protection. Unique edge-triggered inputs improve noise performance.

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Absolute Maximum Ratings[1][2]

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Storage temperature	T_S	−55		150	°C	
Junction temperature	T_J	−55		150	°C	
DC voltage at CANH and CANL pins	V_{CANH}, V_{CANL}	−45		45	V	0 V< V_{DD2} < 5.25 V; indefinite duration
Supply voltage	V_{DD1}, V_{DD2}	−0.3		7	V	
Digital input voltage	V_{TxD}, V_S	−0.3		V_{DD} + 0.3	V	
Digital output voltage	V_{RxD}	−0.3		V_{DD} + 0.3	V	
DC voltage at V_{REF}	V_{REF}	−0.3		V_{DD} + 0.3	V	
Transient voltage at CANH or CANL	$V_{trt(CAN)}$	−150		150	V	
Electrostatic discharge at all pins	V_{esd}	−4000		4000	V	Human body model
Electrostatic discharge at all pins	V_{esd}	−500		500	V	Machine model

Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Supply voltage	V_{DD1} V_{DD2}	3.0 4.75		5.5 5.25	V	
Ambient operating temperature	T_A	−55		125	°C	
Junction temperature	T_J	−55		125	°C	
Input voltage at any bus terminal (separately or common mode)	V_{CANH} V_{CANL}	−12		12	V	
High-level digital input voltage[3][4]	V_{IH}	2.0 2.4 2.0		V_{DD1} V_{DD1} V_{DD2}	V	V_{DD1} = 3.3 V V_{DD1} = 5.0 V V_{DD2} = 5.0 V
Low-level digital input voltage[3][4]	V_{IL}	0		0.8	V	
Digital output current (RxD)	I_{OH}	−8		8	mA	V_{DD1} = 3.3V to 5V
Digital input signal rise and fall times	t_{IR}, t_{IF}			1	µs	

Safety and Approvals

IEC 60747-17 (VDE 0884-17):2021-10 (Basic Isolation; VDE File Number 5016933-4880-0001)

- Isolation voltage (V_{ISO}): 2500 V_{RMS}
- Transient overvoltage (V_{IOTM}): 4000 V_{PK}
- Surge rating: 4000 V
- Each part tested at 1590 V_{PK} for 1 second, 5 pC partial discharge limit.
- Samples tested at 4000 V_{PK} for 60 sec.; then 1358 V_{PK} for 10 sec. with 5 pC partial discharge limit.
- Working Voltage (V_{IORM}; pollution degree 2):

Package	Part No. Suffix	Working Voltage
QSOP16	-1	600 V_{RMS}
Narrow-body SOIC16	-3	700 V_{RMS}
Wide-body SOIC16/True 8™	None	600 V_{RMS}

Safety-Limiting Values	Symbol	Value	Units
Safety rating ambient temperature	T_S	180	°C
Safety rating power (180 °C)	P_S	270	mW
Supply current safety rating (total of supplies)	I_S	54	mA

UL 1577 (Component Recognition Program File Number E207481)

- 2500 V rating
- Each part tested at 3000 V_{RMS} (4243 V_{PK}) for 1 second
- Each lot sample tested at 2500 V_{RMS} (3536 V_{PK}) for 1 minute

Soldering Profile

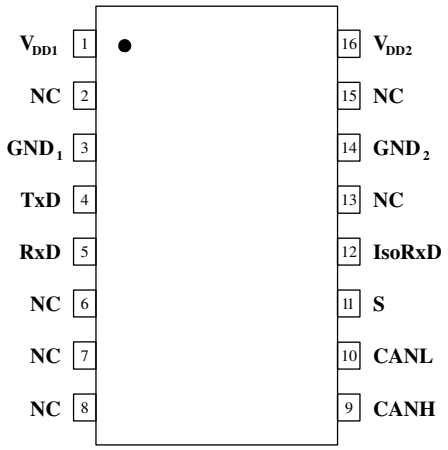
Per JEDEC J-STD-020C; MSL=1

Notes:

1. Absolute Maximum specifications mean the device will not be damaged if operated under these conditions. It does not guarantee performance.
2. All voltages are with respect to network ground except differential I/O bus voltages.
3. The TxD input is edge sensitive. Voltage magnitude of the input signal is specified, but edge rate specifications must also be met.
4. The maximum time allowed for a logic transition at the TxD input is 1 µs.

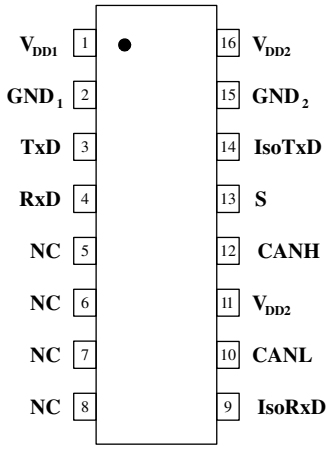
IL41050-1 Pin Connections (QSOP Package)

1	V_{DD1}	V_{DD1} power supply input
2	NC	No internal connection
3	GND_1	V_{DD1} power supply ground return
4	TxD	Transmit Data input
5	RxD	Receive Data output
6	NC	No internal connection
7	NC	No internal connection
8	NC	No internal connection
9	CANH	High level CANbus line
10	CANL	Low level CANbus line
11	S	Mode select input. Leave open or set low for normal operation; set high for silent mode.
12	IsoRxD	Isolated RxD output. No connection should be made to this pin.
13	NC	No internal connection
14	GND_2	Bus ground
15	NC	No internal connection
16	V_{DD2}	Bus power supply input



IL41050-3 Pin Connections (0.15" SOIC Package)

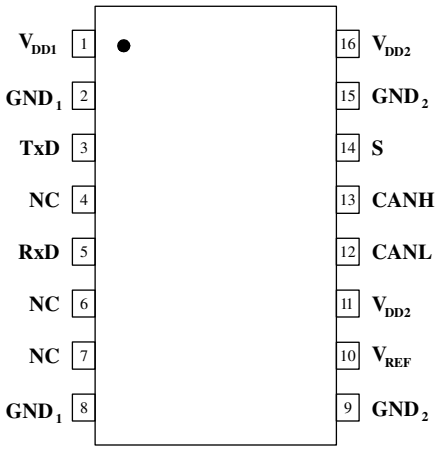
1	V_{DD1}	V_{DD1} power supply input
2	GND_1	V_{DD1} power supply ground return
3	TxD	Transmit Data input
4	RxD	Receive Data output
5	NC	No internal connection
6	NC	No internal connection
7	NC	No internal connection
8	NC	No internal connection
9	IsoRxD	Isolated RxD output. No connection should be made to this pin.
10	CANL	Low level CANbus line
11	V_{DD2}	V_{DD2} CAN I/O bus circuitry power supply input*
12	CANH	High level CANbus line
13	S	Mode select input. Leave open or set low for normal operation; set high for silent mode.
14	IsoTxD	Isolated TxD output. No connection should be made to this pin.
15	GND_2	V_{DD2} power supply ground return
16	V_{DD2}	V_{DD2} isolation power supply input*



*Pin 11 is not internally connected to pin 16; both should be connected to the V_{DD2} power supply for normal operation.

IL41050 Pin Connections (0.3" SOIC Package)

1	V_{DD1}	V_{DD1} power supply input
2	GND_1	V_{DD1} power supply ground return (pin 2 is internally connected to pin 8)
3	TxD	Transmit Data input
4	NC	No internal connection
5	RxD	Receive Data output
6	NC	No internal connection
7	NC	No internal connection
8	GND_1	V_{DD1} power supply ground return (pin 8 is internally connected to pin 2)
9	GND_2	V_{DD2} power supply ground return (pin 9 is internally connected to pin 15)
10	V_{REF}	Reference voltage output (nominally 50% of V_{DD2})
11	V_{DD2}	V_{DD2} CAN I/O bus circuitry power supply input*
12	CANL	Low level CANbus line
13	CANH	High level CANbus line
14	S	Mode select input. Leave open or set low for normal operation; set high for silent mode.
15	GND_2	V_{DD2} power supply ground return (pin 15 is internally connected to pin 9)
16	V_{DD2}	V_{DD2} isolation power supply input*



*Pin 11 is not internally connected to pin 16; both should be connected to the V_{DD2} power supply for normal operation.

Operating Specifications

Electrical Specifications (T_{min} to T_{max} and V_{DD1}, V_{DD2}= 4.75 V to 5.25 V unless otherwise stated)						
Parameter	**Symbol**	**Min.**	**Typ.**	**Max.**	**Units**	**Test Conditions**
Power Supply Current						
Quiescent supply current (recessive)	IQ_{VDD1}	1 0.7	1.75 1.4	3.0 2.0	mA	dr = 0 bps; V_{DD1} = 5 V dr = 0 bps; V_{DD1} = 3.3 V
Dynamic supply current (dominant)	I_{VDD1}	1.2 0.9	2.0 1.6	3.2 2.2	mA	dr = 1 Mbps, R_L= 60Ω; V_{DD1} = 5 V dr = 1 Mbps, R_L= 60Ω; V_{DD1} = 3.3 V
Quiescent supply current (recessive) Dynamic supply current (dominant)	IQ_{VDD2} I_{VDD2}	3.5 26	7 52	12 70	mA	0 bps 1 Mbps, R_L = 60Ω
Transmitter Data input (TxD)[1]						
High level input voltage ↑	V_{IH}	2.4		5.25	V	V_{DD1} = 5 V; recessive
High level input voltage ↑	V_{IH}	2.0		3.6	V	V_{DD1} = 3.3 V; recessive
Low level input voltage ↓	V_{IL}	−0.3		0.8	V	Output dominant
TxD input rise and fall time[2]	t_r			1	µs	10% to 90% 
High level input current	I_{IH}	−10		10	µA	V_{TxD} = V_{DD1}
Low level input current	I_{IL}	10		10	µA	V_{TxD} = 0 V
Mode select input (S)						
High level input voltage	V_{IH}	2.0		V_{DD2} + 0.3	V	Silent mode
Low level input voltage	V_{IL}	−0.3		0.8	V	High-speed mode
High level input current	I_{IH}	20	30	50	µA	V_S = 2 V
Low level input current	I_{IL}	15	30	45	µA	V_S = 0 V
Receiver Data output (RxD)						
High level output current	I_{OH}	−2	−8.5	−20	mA	V_{RxD} = 0.8 V_{DD1}
Low level output current	I_{OL}	2	8.5	20	mA	V_{RxD} = 0.45 V
Failsafe supply voltage[4]	V_{DD2}	3.6		3.9	V	
Reference Voltage output (V_{REF})						
Reference Voltage output	V_{REF}	0.45 V_{DD2}	0.5 V_{DD2}	0.55 V_{DD2}	V	−50 µA<I_{VREF}< +50 µA
Bus lines (CANH and CANL)						
Recessive voltage at CANH pin	$V_{O(reces)}$ CANH	2.0	2.5	3.0	V	V_{TxD} = V_{DD1}, no load
Recessive voltage at CANL pin	$V_{O(reces)}$ CANL	2.0	2.5	3.0	V	V_{TxD} = V_{DD1}, no load
Recessive current at CANH pin	$I_{O(reces)}$ CANH	−2.5		+2.5	mA	−27V < V_{CANH}< +32V; 0V < V_{DD2}<5.25V
Recessive current at CANL pin	$I_{O(reces)}$ CANL	−2.5		+2.5	mA	−27V < V_{CANL} < +32V; 0 V <V_{DD2} < 5.25V
Dominant voltage at CANH pin	$V_{O(dom)}$ CANH	3.0	3.6	4.25	V	V_{TxD} = 0 V
Dominant voltage at CANL pin	$V_{O(dom)}$ CANL	0.5	1.4	1.75	V	V_{TxD} = 0 V
Differential bus input voltage (V_{CANH} − V_{CANL})	$V_{i(dif)(bus)}$	1.5	2.25	3.0	V	V_{TxD} = 0 V; dominant 42.5 Ω < R_L < 60 Ω
		−120	0	+50	mV	V_{TxD} = V_{DD1}; recessive; no load
Short-circuit output current at CANH	$I_{O(sc)}$ CANH	−45	−70	−95	mA	V_{CANH} = 0 V, V_{TxD} = 0
Short-circuit output current at CANL	$I_{O(sc)}$ CANL	45	70	120	mA	V_{CANL} = 36 V, V_{TxD} = 0
Differential receiver threshold voltage	$V_{i(dif)(th)}$	0.5	0.7	0.9	V	−5 V <V_{CANL}< +10 V; −5 V <V_{CANH}< +10 V
Differential receiver input voltage hysteresis	$V_{i(dif)(hys)}$	50	70	100	mV	−5 V <V_{CANL}< +10 V; −5 V <V_{CANH}< +10 V
Common Mode input resistance at CANH	$R_{i(CM)(CANH)}$	15	25	37	kΩ	
Common Mode input resistance at CANL	$R_{i(CM)(CANL)}$	15	25	37	kΩ	
Matching between Common Mode input resistance at CANH, CANL	$R_{i(CM)(m)}$	−3	0	+3	%	V_{CANL} = V_{CANH}

Electrical Specifications (T_{min} to T_{max} and V_{DD1}, V_{DD2}= 4.5 V to 5.5 V unless otherwise stated)						
Parameter	**Symbol**	**Min.**	**Typ.**	**Max.**	**Units**	**Test Conditions**
Bus lines (….cont)						
Differential input resistance	$R_{i(diff)}$	25	50	75	kΩ	
Input capacitance, CANH	$C_{i(CANH)}$		7.5	20	pF	$V_{TxD} = V_{DD1}$
Input capacitance, CANL	$C_{i(CANL)}$		7.5	20	pF	$V_{TxD} = V_{DD1}$
Differential input capacitance	$C_{i(dif)}$		3.75	10	pF	$V_{TxD} = V_{DD1}$
Input leakage current at CANH	$I_{LI(CANH)}$	100	170	250	µA	V_{CANH}= 5 V, V_{DD2}= 0
Input leakage current at CANL	$I_{LI(CANL)}$	100	170	250	µA	V_{CANL}= 5 V, V_{DD2}= 0
Thermal Shutdown						
Shutdown junction temperature	$T_{j(SD)}$	155	165	180	°C	

Timing Characteristics (60 Ω / 100 pF bus loading; 20 pF RxD load; see Fig. 1)						
Parameter	**Symbol**	**Min.**	**Typ.**	**Max.**	**Units**	**Test Conditions**
TxD to bus active delay	$t_{d(TxD-BUSon)}$	44 36	93 96	160 128	ns	V_S= 0 V; V_{DD1} = 5 V V_S = 0 V; V_{DD1} = 3.3 V
TxD to bus inactive delay	$t_{d(TxD-BUSoff)}$	34 37	68 71	110 113	ns	V_S = 0 V; V_{DD1} = 5 V V_S = 0 V; V_{DD1} = 3.3 V
Bus active to RxD delay	$t_{d(BUSon-RxD)}$	29 32	63 66	125 128	ns	V_S = 0 V; V_{DD1} = 5 V V_S = 0 V; V_{DD1} = 3.3 V
Bus inactive to RxD delay	$t_{d(BUSoff-RxD)}$	69 72	108 111	170 173	ns	V_S = 0 V; V_{DD1} = 5 V V_S = 0 V; V_{DD1} = 3.3 V
Loop delay low-to-high or high-to-low	T_{LOOP}	74	180	250	ns	V_S = 0 V; "Typ." at 25°C and nominal loads
TxD dominant time for timeout	$T_{dom(TxD)}$	250	457	765	µs	V_{TxD} = 0 V 3.0 V > V_{DD1} < 5.5 V
Common Mode Transient Immunity (TxD Logic High or Logic Low)	$\|CM_H\|$,$\|CM_L\|$	30	50		kV/µs	R_L = 60 Ω; V_{CM} = 1500 V_{DC}; $t_{TRANSIENT}$ = 25 ns

Magnetic Field Immunity(3) (V_{DD2}= 5V, 3V<V_{DD1}<5.5V)						
Power Frequency Magnetic Immunity	H_{PF}		6000		A/m	50Hz/60 Hz
Pulse Magnetic Field Immunity	H_{PM}		7000		A/m	t_p = 8 µs
Damped Oscillatory Magnetic Field	H_{OSC}		7000		A/m	0.1 Hz – 1 MHz
Cross-axis Immunity Multiplier	K_X		2			See Fig. 4

Insulation Specifications

Parameter		**Symbol**	**Min.**	**Typ.**	**Max.**	**Units**	**Test Conditions**
Creepage distance (external)	IL41050TA-1E (QSOP) IL41050TA-3E (0.15" SOIC) IL41050TAE (0.3" SOIC)		3.2 4.0 8.03	 8.3		mm Per IEC 60601
Total barrier thickness (internal)			0.012	0.013		mm	
Barrier resistance		R_{IO}		$>10^{14}$		Ω	500 V
Barrier capacitance		C_{IO}		7		pF	f = 1 MHz
Leakage current				0.2		$µA_{RMS}$	240 V_{RMS}, 60 Hz
Comparative Tracking Index		CTI	≥175			V	Per IEC 60112
High voltage endurance (maximum barrier voltage for indefinite life)	AC DC	V_{IO}	1000 1500			V_{RMS} V_{DC}	At maximum operating temperature
Barrier life				44000		Years	100°C, 1000 V_{RMS}, 60% CL activation energy

Thermal Characteristics

Parameter		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Junction–Ambient Thermal Resistance	QSOP 0.15" SOIC 0.3" SOIC	θ_{JA}		100 82 55		°C/W	Per JESD51; 2s2p board in free air
Junction–Case (Top) Thermal Resistance	QSOP 0.15" SOIC 0.3" SOIC	θ_{JC}		9 8 12		°C/W	
Power Dissipation	QSOP 0.15" SOIC 0.3" SOIC	P_D			675 700 800	mW	

Insulation Specifications

Parameter		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Creepage distance (external)	IL41050TA-1E (QSOP) IL41050TA-3E (0.15" SOIC) IL41050TAE (0.3" SOIC)		3.2 4.0 8.03	8.3		mm	Per IEC 60601
Total barrier thickness (internal)			0.012	0.013		mm	
Barrier resistance		R_{IO}		$>10^{14}$		Ω	500 V
Barrier capacitance		C_{IO}		7		pF	f = 1 MHz
Leakage current				0.2		μA_{RMS}	240 V_{RMS}, 60 Hz
Comparative Tracking Index		CTI	≥175			V	Per IEC 60112
High voltage endurance (maximum barrier voltage for indefinite life)	AC DC	V_{IO}	1000 1500			V_{RMS} V_{DC}	At maximum operating temperature
Barrier life				44000		Years	100°C, 1000 V_{RMS}, 60% CL activation energy

Thermal Characteristics

Parameter		Symbol	Min.	Typ.	Max.	Units	Test Conditions
Junction–Ambient Thermal Resistance	QSOP 0.15" SOIC 0.3" SOIC	θ_{JA}		100 82 67		°C/W	Double-sided PCB in free air
Junction–Case (Top) Thermal Resistance	QSOP 0.15" SOIC 0.3" SOIC	θ_{JC}		9 8 12			
Junction–Ambient Thermal Resistance	0.3" SOIC	θ_{JA}		46			2s2p PCB in free air per JESD51
Junction–Case (Top) Thermal Resistance		θ_{JC}		9			
Power Dissipation	QSOP 0.15" SOIC 0.3" SOIC	P_D			675 700 1500	mW	

Notes:

1. The TxD input is edge sensitive. Voltage magnitude of the input signal is specified, but edge rate specifications must also be met.
2. The maximum time allowed for a logic transition at the TxD input is 1 µs.
3. Test and measurement methods are given in the Electromagnetic Compatibility section.
4. If V_{DD2} falls below the specified failsafe supply voltage, RxD will go High.

Timing Test Circuit

Timing parameters are measured with 60 Ω / 100 pF bus line loading and 20 pF on RxD as shown in Figure 1 below:

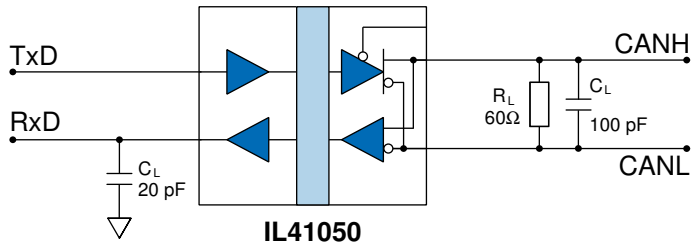


Figure 1. Timing characteristics test circuit.

Block Diagram

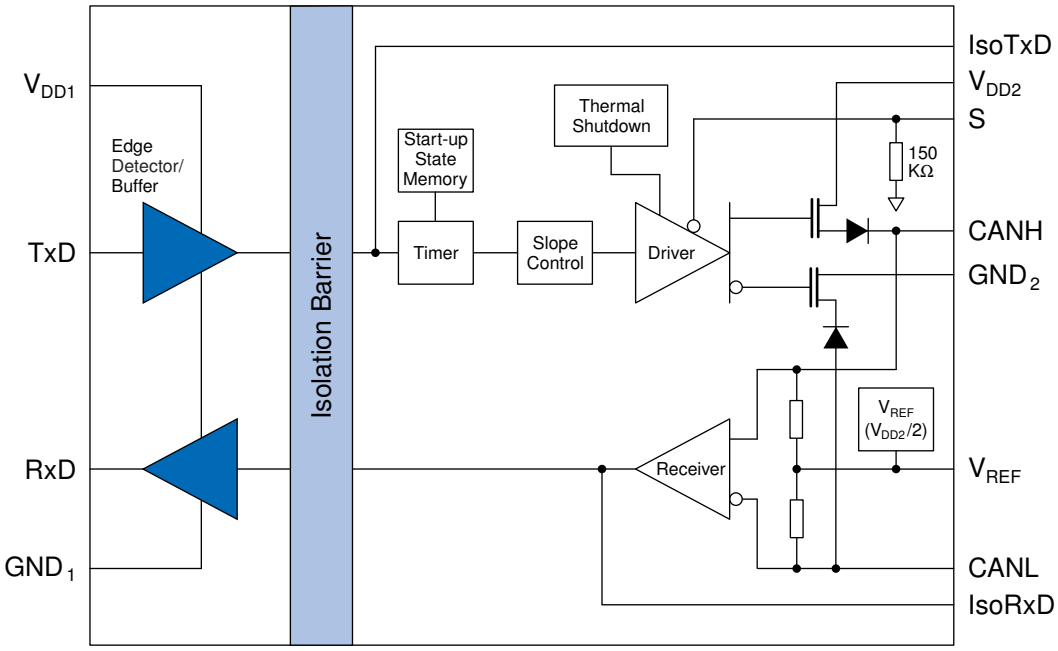


Figure 2. IL41050TA detailed functional diagram.

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Application Information

As Figure 3 shows, the IL41050TA can provide isolation and level shifting between a 5 volt CAN bus and a 3 volt microcontroller:

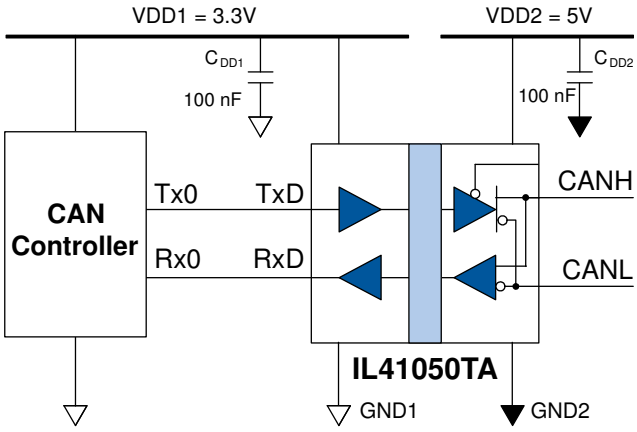


Figure 3. Isolated CAN node using the IL41050TA.

Bus-Side Power Supply Pins

On the 0.3" SOIC version, both V_{DD2} power supply inputs (pins 11 and 16) must be connected to the bus-side power supply. On some parts the CAN I/O circuitry and bus-side isolation circuitry power are separated for testing purposes. The part may not operate without both pins powered, and operation without both pins powered can cause damage.

Power Supply Decoupling

V_{DD1} and V_{DD2} should be bypassed with 0.1 µF capacitors as close as possible to the V_{DD} pins.

Maintaining Creepage

Creepage distances are often critical in isolated circuits. In addition to meeting JEDEC standards, NVE isolator packages have unique creepage specifications. Standard pad libraries often extend under the package, compromising creepage and clearance. Similarly, ground planes, if used, should be spaced to avoid compromising clearance. Package drawings and recommended pad layouts are included in this datasheet.

Input Configurations

The TxD input should not be left open as the state will be indeterminate. If connected to an open-drain or open collector output, a pull-up resistor (typically 16 kΩ) should be connected from the input to V_{DD1}.

The Mode Select ("S") input has a nominal 150 kΩ internal pull-down resistor. It can be left open or set low for normal operation.

Dominant Mode Time-out and Failsafe Receiver Functions

CAN bus latch up is prevented by an integrated Dominant mode timeout function. If the TxD pin is forced permanently low by hardware or software application failure, the time-out returns the RxD output to the high state no more than 765 µs after TxD is asserted dominant. The timer is triggered by a negative edge on TxD. If the duration of the low is longer than the internal timer value, the transmitter is disabled, driving the bus to the recessive state. The timer is reset by a positive edge on pin TxD.

If power is lost on Vdd2, the IL41050 asserts the RxD output high when the supply voltage falls below 3.8 V. RxD will return to normal operation when Vdd2 rises above approximately 4.2 V.

Programmable Power-Up

A unique non-volatile programmable power-up feature prevents unstable nodes. A state that needs to be present at node power up can be programmed at the last power down. For example, if a CAN node is required to "pulse" dominant at power up, TxD can be sent low by the controller immediately prior to power down. When power is resumed, the node will immediately go dominant allowing self-check code in the microcontroller to verify node operation. If desired, the node can also power up silently by presetting the TxD line high at power down. At the next power on, the IL41050 will remain silent, awaiting a dominant state from the bus.

The microcontroller can check that the CAN node powered down correctly before applying power at the next "power on" request. If the node powered down as intended, RxD will be set high and stored in the IL41050's non-volatile memory. The level stored in the RxD bit can be read before isolated node power is enabled, avoiding possible CAN bus disruption due to an unstable node.

Replacing Non-Isolated Transceivers

The IL41050 is designed to replace common non-isolated CAN transceivers such as the Philips/NXP TJA1050 with minimal circuit changes. Some notable differences:

- Some non-isolated CAN transceivers have internal TxD pull-up resistors, but the IL41050 TxD input should not be left open. If connected to an open-drain or open collector output, a pull-up resistor (typically 16 kΩ) should be connected from the input to V_{DD1}.

- Initialization behavior varies between CAN transceivers. To ensure the desired power-up state, the IL41050 should be initialized with a TxD pulse (low-to-high for recessive initialization), or shut down the transceiver in the desired power-up state (the "programmable power-up feature").

- Many non-isolated CAN transceivers have a V_{REF} output. Such a reference is available on the IL41050 wide-body version.

The VREF Output

V_{REF} is a reference voltage output used to drive bus threshold comparators in some legacy systems and is provided on the IL41050 wide-body version. The output is half of the bus supply ±10% (*i.e.,* $0.45\ V_{DD2} < V_{REF} < 0.55\ V_{DD2}$), and can drive up to 50 µA.

IsoRxD / IsoTxD Outputs

The IsoRxD and IsoTxD outputs are isolated versions of the RxD and TxD signals. These outputs are provided for troubleshooting on the narrow-body version, but normally no connections should be made to the pins.

The Isolation Advantage

Battery fire caused by over or under charging of individual lithium-ion cells is a major concern in multi-cell high voltage electric and hybrid vehicle batteries. To combat this, each cell is monitored for current flow, cell voltage, and in some advanced batteries, magnetic susceptibility. The IL41050 allows seamless connection of the monitoring electronics of every cell to a common CAN bus by electrically isolating inputs from outputs, effectively isolating each cell from all other cells. Cell status is then monitored via the CAN controller in the Battery Management System (BMS).

Another major advantage of isolation is the tremendous increase in noise immunity it affords the CAN node, even if the power source is a battery. Inductive drives and inverters can produce transient swings in excess of 20 kV/µs. The traditional, non-isolated CAN node provides some protection due to differential signaling and symmetrical driver/receiver pairs, but the IL41050 typically provides more than twice the dV/dt protection of a traditional CAN node.

Electrostatic Discharge Sensitivity

This product has been tested for electrostatic sensitivity to the limits stated in the specifications. However, NVE recommends that all integrated circuits be handled with appropriate care to avoid damage. Damage caused by inappropriate handling or storage could range from performance degradation to complete failure.

Electromagnetic Compatibility

The IL41050TA is fully compliant with IEC 61000-6-1 and IEC 61000-6-2 standards for immunity, and IEC 61000-6-3, IEC 61000-6-4, CISPR, and FCC Class A standards for emissions.

Immunity to external magnetic fields is higher if the field direction is “end-to-end” (rather than to “pin-to-pin”) as shown in the diagram below:

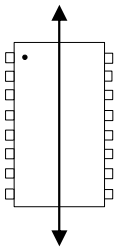
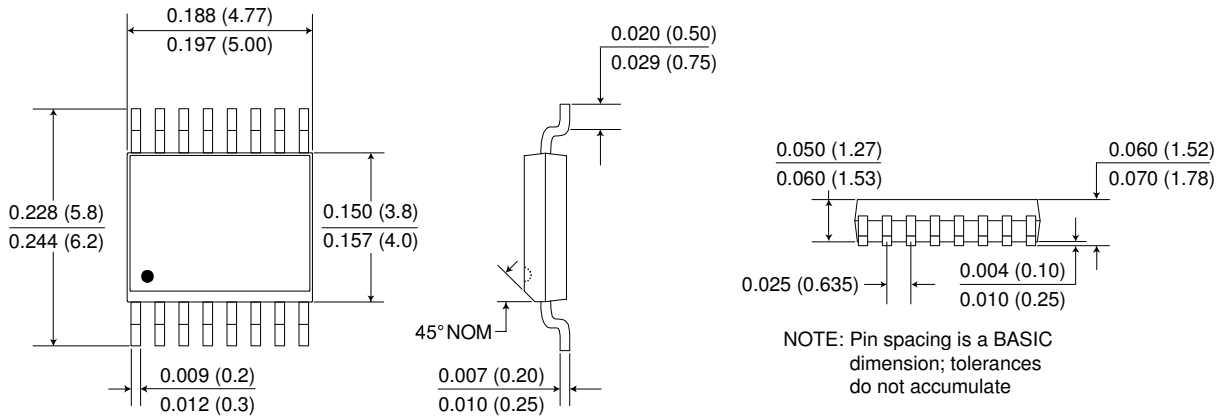


Figure 4. Orientation for high field immunity.

Package Drawings

Ultraminiature 16-pin QSOP Package (-1 suffix)

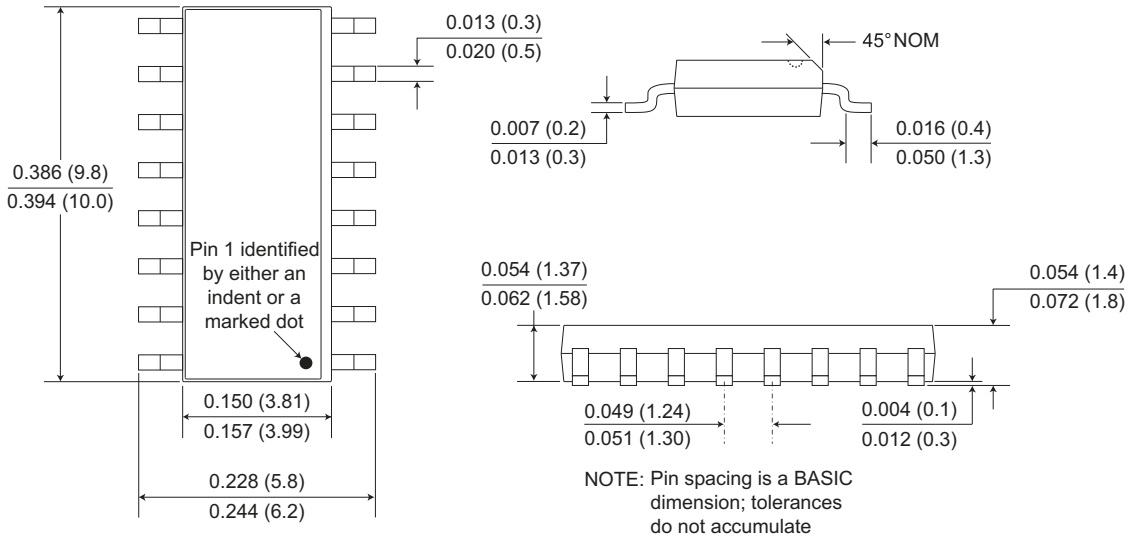
Dimensions in inches (mm); scale = approx. 5X



NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

0.15" 16-pin SOIC Package (-3 suffix)

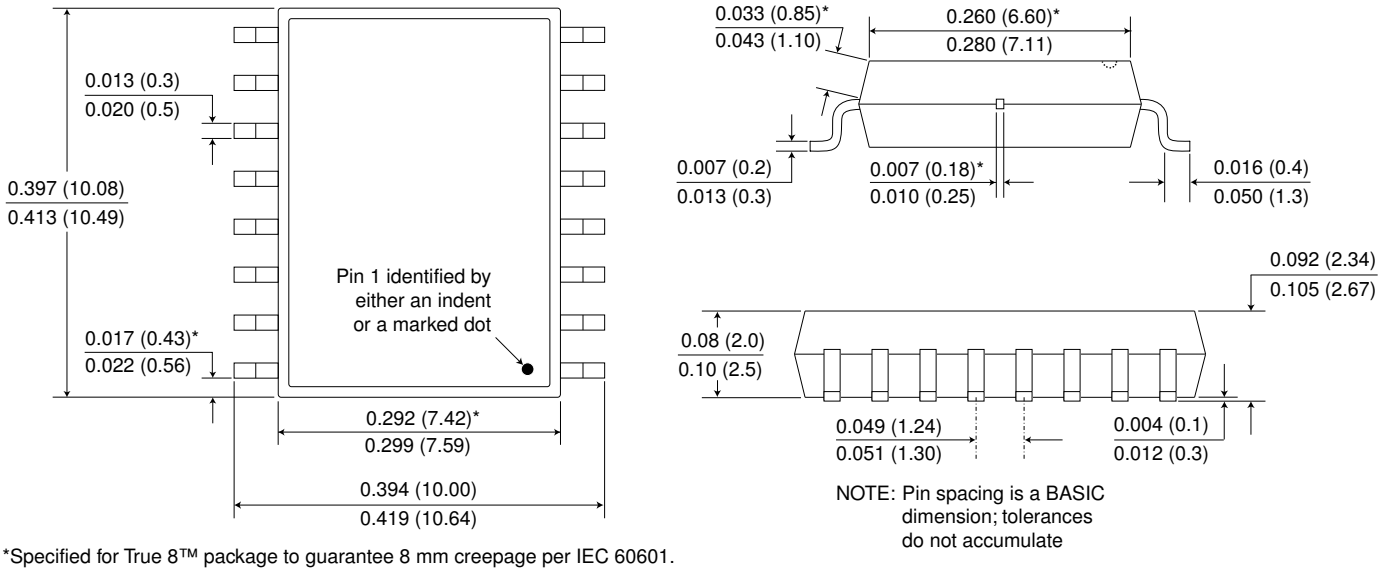
Dimensions in inches (mm); scale = approx. 5X



NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

0.3" 16-pin SOIC Package (no suffix)

Dimensions in inches (mm); scale = approx. 5X



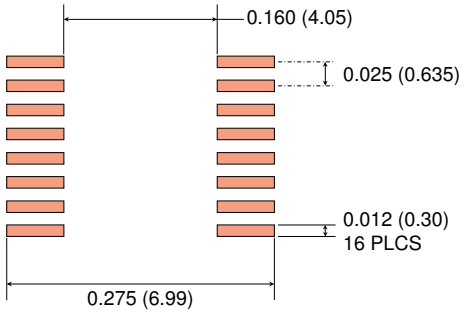
NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

*Specified for True 8™ package to guarantee 8 mm creepage per IEC 60601.

Recommended Pad Layouts

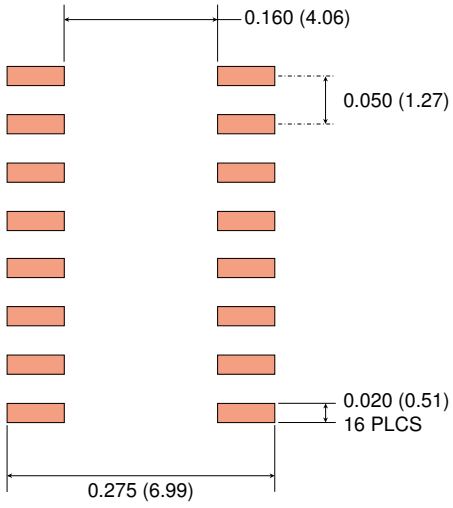
4 mm x 5 mm 16-pin QSOP Pad Layout

Dimensions in inches (mm); scale = approx. 5X



0.15" 16-pin SOIC Pad Layout

Dimensions in inches (mm); scale = approx. 5X



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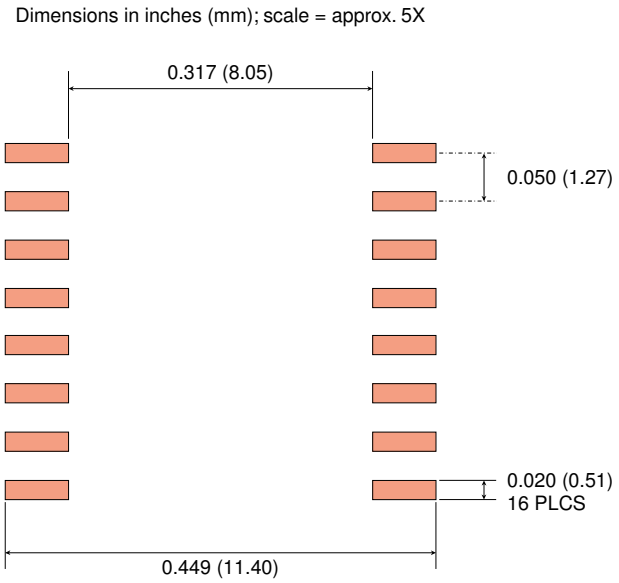
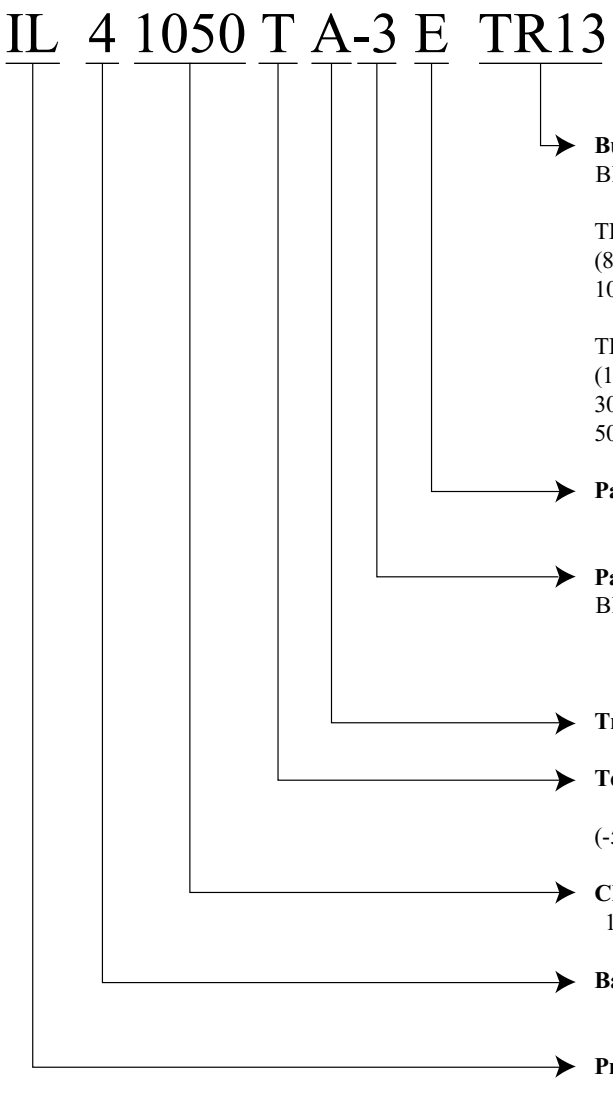
0.3" 16-pin SOIC Pad Layout



Ordering Information and Valid Part Numbers



Bulk Packaging
Blank = Tube (50 pcs)

TR7 = 7" Tape and Reel
(800 pcs 0.15" SOIC or
1000 pcs QSOP)

TR13 = 13" Tape and Reel
(1500 pcs 0.3" SOIC,
3000 pcs 0.15" SOIC, or
5000 pcs QSOP)

Package
E = RoHS Compliant

Package Type
Blank = 0.3" SOIC
-3 = 0.15" SOIC
-1 = 0.15" QSOP

Transceiver Revision

Temperature Range
T = Extended
(-55˚C to +125˚C)

Channel Configuration
1050 = CAN Transceiver

Base Part Number
4 = Isolated Transceiver

Product Family
IL = Isolators

Valid Part Numbers
IL41050TAE
IL41050TAE TR13
IL41050TA-3E
IL41050TA-3E TR7
IL41050TA-3E TR13
IL41050TA-1E
IL41050TA-1E TR7
IL41050TA-1E TR13

RoHS COMPLIANT

Revision History

ISB-DS-001-IL41050TA-M
February 2023

Change
- Updated maximum package thickness for 16-pin QSOP package (-1 suffix) (p. 13).

ISB-DS-001-IL41050TA-L
October 2022

Changes
- Upgrade to VDE 0884-17 (p. 3).
- Increased Working Voltage ratings based on latest VDE testing (p. 3)
- Improved thermal characteristics (p.8).
- Updated EMC standards.
- Deleted minimum magnetic field immunity specifications (p. 7) since it is not 100% tested.

ISB-DS-001-IL41050TA-K
November 2016

Change
- Updated from IEC 60747-5-5 (VDE 0884) certification to VDE V 0884-10.

ISB-DS-001-IL41050TA-J
June 2014

Changes
- Increased QSOP creepage specification from 2.75 mm to 3.2 mm (p. 2).
- Clarified note that pins 11 and 16 on the 0.3" SOIC version should both be connected (p. 9).

ISB-DS-001-IL41050TA-I
April 2014

Changes
- Added QSOP version (-1 suffix).
- Revised and added details to thermal characteristic specifications (p. 2).
- Added VDE 0884 Safety-Limiting Values (p. 3).

ISB-DS-001-IL41050TA-H
November 2013

Changes
- IEC 60747-5-5 (VDE 0884) certification.
- Upgraded from MSL 2 to MSL 1.

ISB-DS-001-IL41050TA-G
June 2013

Changes
- Added VDE 0884 pending.
- Added transient immunity specifications.
- Added high voltage endurance specification (p. 2).
- Increased magnetic immunity specifications (p. 6).
- Updated package drawings.
- Added recommended solder pad layouts.

ISB-DS-001-IL41050TA-F
January 2013

Changes
- Added thermal characteristics (p. 2).
- Cosmetic changes.

ISB-DS-001-IL41050TA-E
December 2012

Changes
- UL 1577 recognition and IEC 61010-1 approval.
- Detailed isolation and barrier specifications.
- Style and cosmetic changes.

ISB-DS-001-IL41050TA-D
October 2012

Changes
- Changed title to highlight speed.
- Added block diagram (detailed functional diagram).
- Rearranged and repaginated.

ISB-DS-001-IL41050TA-C
July 2012

Changes
- Tightened and clarified typical loop delay specification.
- Clarified IsoRxD / IsoTxD outputs on narrow-body package.

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ISB-DS-001-IL41050TA-M

February 2023